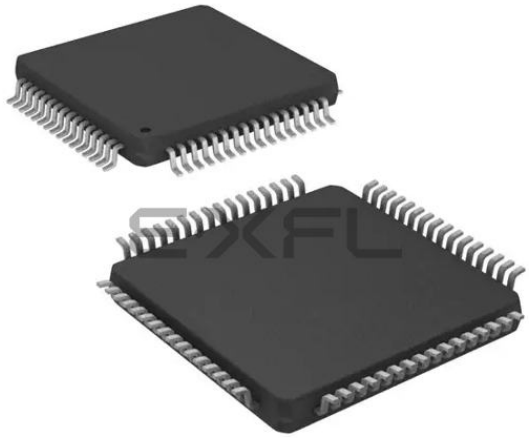
Microchip Technology - DSPIC33EP128GP506-I/PT Datasheet



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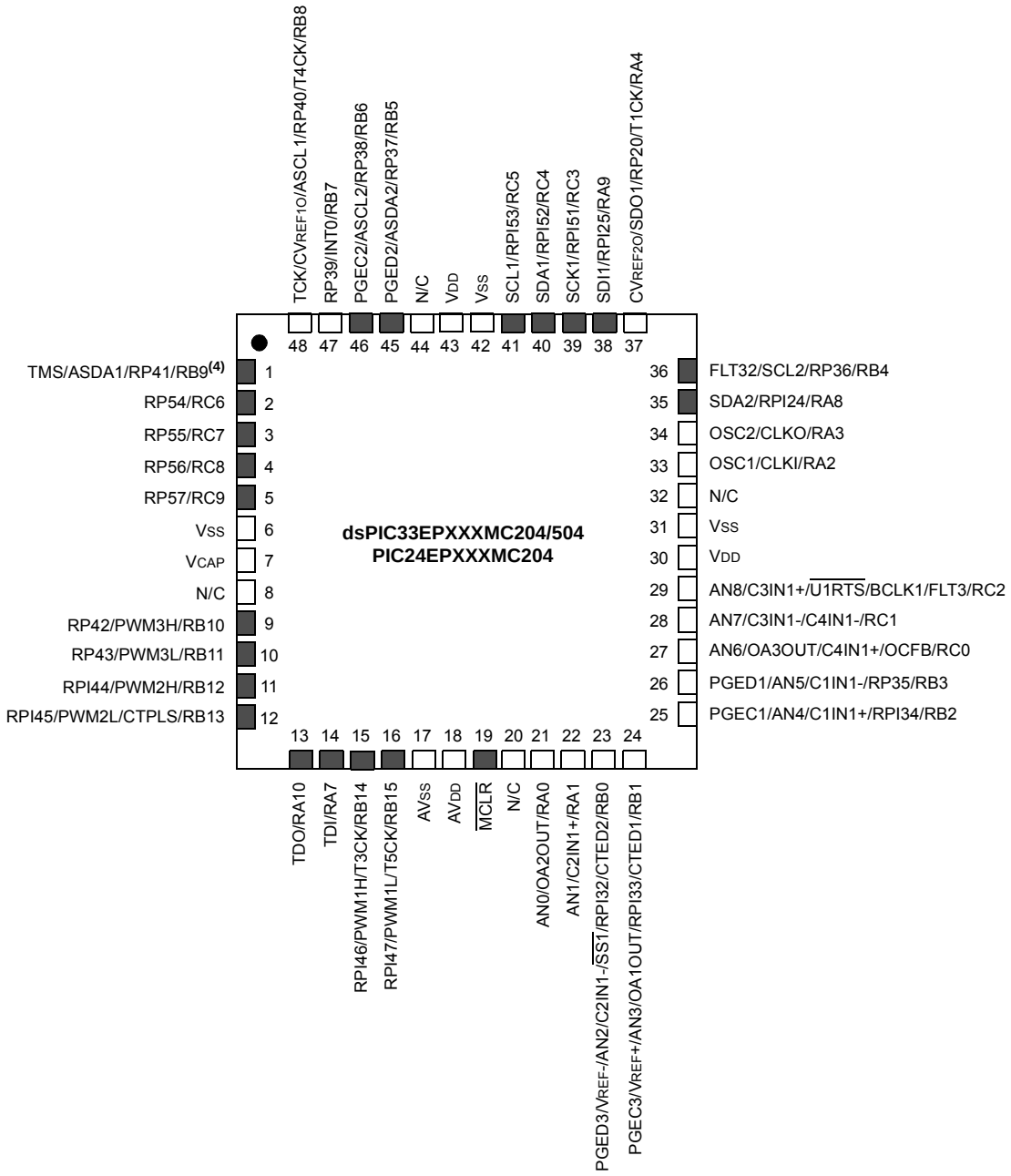
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 16x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep128gp506-i-pt

Pin Diagrams (Continued)

48-Pin UQFN(1,2,3)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

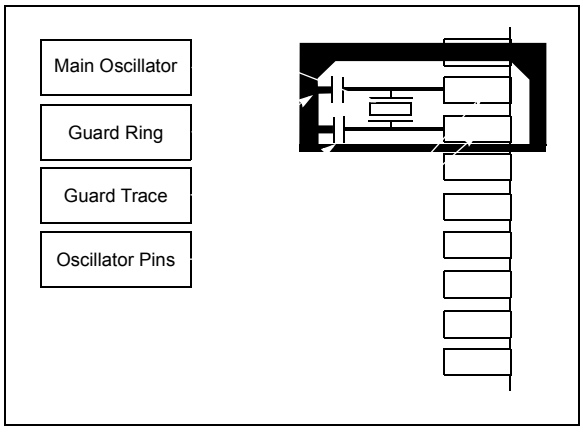
- *"Using MPLAB® ICD 3"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) DS51749

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency Primary Oscillator and a low-frequency Secondary Oscillator. For details, see **Section 9.0 "Oscillator Configuration"** for details.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



REGISTER 3-2: CORCON: CORE CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1(1)	US0(1)	EDT(1,2)	DL2(1)	DL1(1)	DL0(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA(1)	SATB(1)	SATDW(1)	ACCSAT(1)	IPL3(3)	SFA	RND(1)	IF(1)
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing latency is enabled
0 = Fixed exception processing latency is enabled

bit 14 **Unimplemented:** Read as '0'

bit 13-12 **US<1:0>:** DSP Multiply Unsigned/Signed Control bits(1)
11 = Reserved
10 = DSP engine multiplies are mixed-sign
01 = DSP engine multiplies are unsigned
00 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit(1,2)
1 = Terminates executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits(1)
111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit(1)
1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit(1)
1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit(1)
1 = Data Space write saturation is enabled
0 = Data Space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit(1)
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(3)
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.
2: This bit is always read as '0'.
3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

TABLE 4-10: OUTPUT COMPARE 1 THROUGH OUTPUT COMPARE 4 REGISTER MAP

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1CON1	0900	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC1CON2	0902	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC1RS	0904	Output Compare 1 Secondary Register																xxxx
OC1R	0906	Output Compare 1 Register																xxxx
OC1TMR	0908	Timer Value 1 Register																xxxx
OC2CON1	090A	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC2CON2	090C	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC2RS	090E	Output Compare 2 Secondary Register																xxxx
OC2R	0910	Output Compare 2 Register																xxxx
OC2TMR	0912	Timer Value 2 Register																xxxx
OC3CON1	0914	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC3CON2	0916	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC3RS	0918	Output Compare 3 Secondary Register																xxxx
OC3R	091A	Output Compare 3 Register																xxxx
OC3TMR	091C	Timer Value 3 Register																xxxx
OC4CON1	091E	—	—	OCSIDL	OCTSEL<2:0>			—	ENFLTB	ENFLTA	—	OCFLTB	OCFLTA	TRIGMODE	OCM<2:0>			0000
OC4CON2	0920	FLTMD	FLTOUT	FLTTRIEN	OCINV	—	—	—	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL<4:0>					000C
OC4RS	0922	Output Compare 4 Secondary Register																xxxx
OC4R	0924	Output Compare 4 Register																xxxx
OC4TMR	0926	Timer Value 4 Register																xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 5-1: NVMCON: NONVOLATILE MEMORY (NVM) CONTROL REGISTER

R/SO-0(1)	R/W-0(1)	R/W-0(1)	R/W-0	U-0	U-0	U-0	U-0
WR	WREN	WRERR	NVMSIDL(2)	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)
—	—	—	—	NVMOP3(3,4)	NVMOP2(3,4)	NVMOP1(3,4)	NVMOP0(3,4)
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **WR:** Write Control bit(1)
- 1 = Initiates a Flash memory program or erase operation; the operation is self-timed and the bit is cleared by hardware once the operation is complete
- 0 = Program or erase operation is complete and inactive

bit 14 **WREN:** Write Enable bit(1)
- 1 = Enables Flash program/erase operations
- 0 = Inhibits Flash program/erase operations

bit 13 **WRERR:** Write Sequence Error Flag bit(1)
- 1 = An improper program or erase sequence attempt or termination has occurred (bit is set automatically on any set attempt of the WR bit)
- 0 = The program or erase operation completed normally

bit 12 **NVMSIDL:** NVM Stop in Idle Control bit(2)
- 1 = Flash voltage regulator goes into Standby mode during Idle mode
- 0 = Flash voltage regulator is active during Idle mode

bit 11-4 **Unimplemented:** Read as '0'

bit 3-0 **NVMOP<3:0>:** NVM Operation Select bits(1,3,4)
- 1111 = Reserved
- 1110 = Reserved
- 1101 = Reserved
- 1100 = Reserved
- 1011 = Reserved
- 1010 = Reserved
- 0011 = Memory page erase operation
- 0010 = Reserved
- 0001 = Memory double-word program operation(5)
- 0000 = Reserved

Note 1: These bits can only be reset on a POR.

2: If this bit is set, there will be minimal power savings (I_{IDLE}) and upon exiting Idle mode, there is a delay (T_{VREG}) before Flash memory becomes operational.

3: All other combinations of NVMOP<3:0> are unimplemented.

4: Execution of the PWRSAV instruction is ignored while any of the NVM operations are in progress.

5: Two adjacent words on a 4-word boundary are programmed during execution of this operation.

REGISTER 7-1: SR: CPU STATUS REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/C-0	R/C-0	R-0	R/W-0
OA	OB	SA	SB	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL<2:0>(2)			RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1'= Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits(2,3)

111 = CPU Interrupt Priority Level is 7 (15); user interrupts are disabled
110 = CPU Interrupt Priority Level is 6 (14)
101 = CPU Interrupt Priority Level is 5 (13)
100 = CPU Interrupt Priority Level is 4 (12)
011 = CPU Interrupt Priority Level is 3 (11)
010 = CPU Interrupt Priority Level is 2 (10)
001 = CPU Interrupt Priority Level is 1 (9)
000 = CPU Interrupt Priority Level is 0 (8)

Note 1: For complete register details, see Register 3-1.

2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL, if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.

3: The IPL<2:0> Status bits are read-only when the NSTDIS bit (INTCON1<15>) = 1.

REGISTER 10-6: PMD7: PERIPHERAL MODULE DISABLE CONTROL REGISTER 7

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
—	—	—	DMA0MD(1) DMA1MD(1) DMA2MD(1) DMA3MD(1)	PTGMD	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as '0'

bit 4 **DMA0MD:** DMA0 Module Disable bit(1)
1 = DMA0 module is disabled
0 = DMA0 module is enabled

DMA1MD: DMA1 Module Disable bit(1)
1 = DMA1 module is disabled
0 = DMA1 module is enabled

DMA2MD: DMA2 Module Disable bit(1)
1 = DMA2 module is disabled
0 = DMA2 module is enabled

DMA3MD: DMA3 Module Disable bit(1)
1 = DMA3 module is disabled
0 = DMA3 module is enabled

bit 3 **PTGMD:** PTG Module Disable bit
1 = PTG module is disabled
0 = PTG module is enabled

bit 2-0 **Unimplemented:** Read as '0'

Note 1: This single bit enables and disables all four DMA channels.

11.7 Peripheral Pin Select Registers

REGISTER 11-1: RPINR0: PERIPHERAL PIN SELECT INPUT REGISTER 0

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INT1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-8 **INT1R<6:0>:** Assign External Interrupt 1 (INT1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 11-15: RPINR37: PERIPHERAL PIN SELECT INPUT REGISTER 37 (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	SYNCI1R<6:0>						
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **SYNCI1R<6:0>:** Assign PWM Synchronization Input 1 to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7-0 **Unimplemented:** Read as '0'

REGISTER 11-18: RPOR0: PERIPHERAL PIN SELECT OUTPUT REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP35R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP20R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP35R<5:0>:** Peripheral Output Function is Assigned to RP35 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP20R<5:0>:** Peripheral Output Function is Assigned to RP20 Output Pin bits (see Table 11-3 for peripheral function numbers)

REGISTER 11-19: RPOR1: PERIPHERAL PIN SELECT OUTPUT REGISTER 1

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP37R<5:0>					
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP36R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

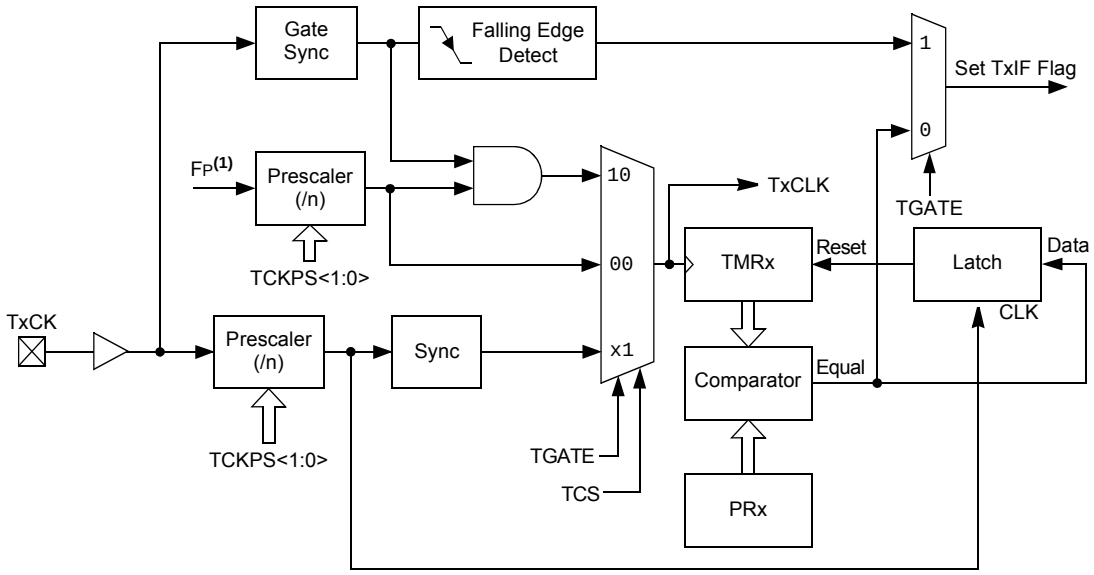
bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP37R<5:0>:** Peripheral Output Function is Assigned to RP37 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-6 **Unimplemented:** Read as ‘0’

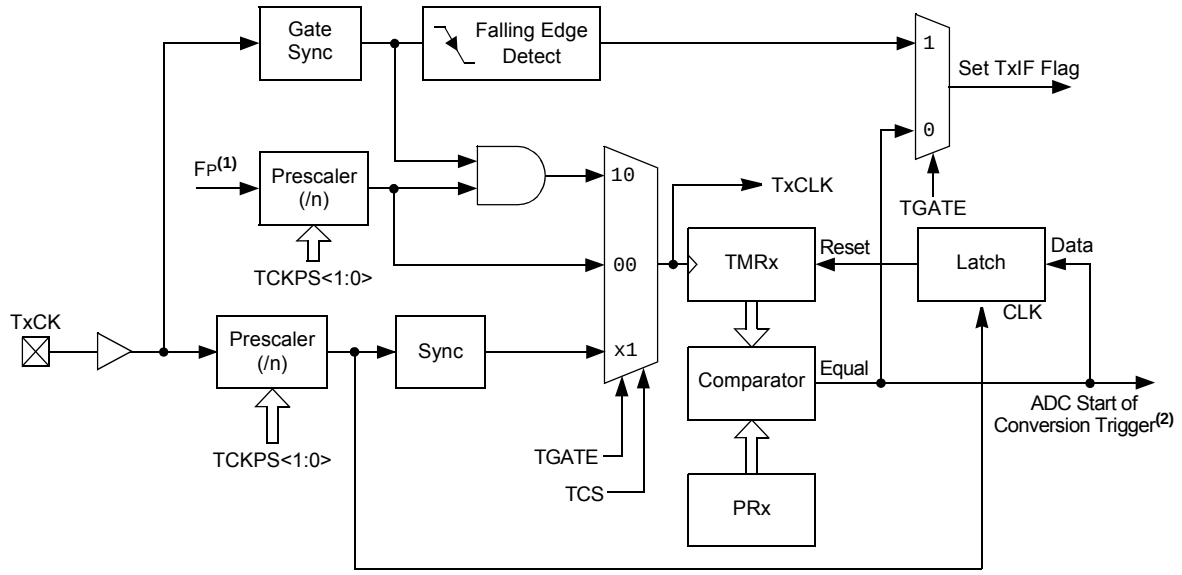
bit 5-0 **RP36R<5:0>:** Peripheral Output Function is Assigned to RP36 Output Pin bits (see Table 11-3 for peripheral function numbers)

FIGURE 13-1: TYPE B TIMER BLOCK DIAGRAM (x = 2 AND 4)



Note 1: FP is the peripheral clock.

FIGURE 13-2: TYPE C TIMER BLOCK DIAGRAM (x = 3 AND 5)



Note 1: FP is the peripheral clock.
2: The ADC trigger is available on TMR3 and TMR5 only.

17.1 QEI Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en555464

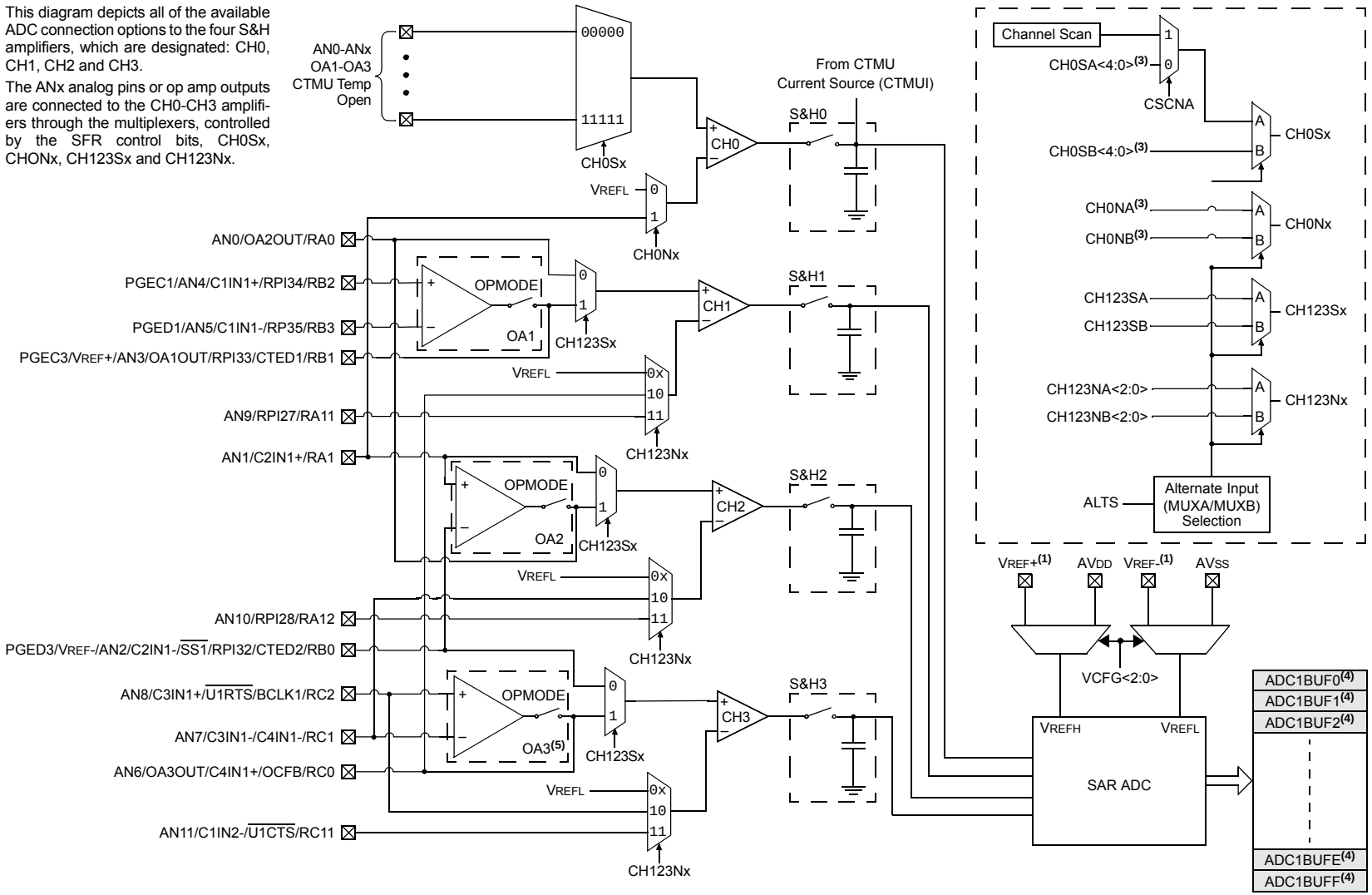
17.1.1 KEY RESOURCES

- **"Quadrature Encoder Interface"** (DS70601) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 23-1: ADC MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CHONx, CH123Sx and CH123Nx.



Note 1: VREF+, VREF- inputs can be multiplexed with other analog inputs.
2: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
3: These bits can be updated with Step commands from the PTG module. See **Section 24.0 "Peripheral Trigger Generator (PTG) Module"** for more information.
4: When ADDMAEN (AD1CON4<8>) = 1, enabling DMA, only ADC1BUF0 is used.
5: OA3 is not available for 28-pin devices.

REGISTER 23-6: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER (CONTINUED)

bit 4-0 **CH0SA<4:0>:** Channel 0 Positive Input Select for Sample MUXA bits(1)

11111 = Open; use this selection with CTMU capacitive and time measurement
11110 = Channel 0 positive input is connected to the CTMU temperature measurement diode (CTMU TEMP)
11101 = Reserved
11100 = Reserved
11011 = Reserved
11010 = Channel 0 positive input is the output of OA3/AN6(2,3)
11001 = Channel 0 positive input is the output of OA2/AN0(2)
11000 = Channel 0 positive input is the output of OA1/AN3(2)
10110 = Reserved
•
•
•
10000 = Reserved
01111 = Channel 0 positive input is AN15(1,3)
01110 = Channel 0 positive input is AN14(1,3)
01101 = Channel 0 positive input is AN13(1,3)
•
•
•
00010 = Channel 0 positive input is AN2(1,3)
00001 = Channel 0 positive input is AN1(1,3)
00000 = Channel 0 positive input is AN0(1,3)

Note 1: AN0 through AN7 are repurposed when comparator and op amp functionality is enabled. See Figure 23-1 to determine how enabling a particular op amp or comparator affects selection choices for Channels 1, 2 and 3.

2: The OAx input is used if the corresponding op amp is selected (OPMODE (CMxCON<10>) = 1); otherwise, the ANx input is used.

3: See the **"Pin Diagrams"** section for the available analog channels for each device.

REGISTER 24-6: PTGSDLIM: PTG STEP DELAY LIMIT REGISTER(1,2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGSDLIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGSDLIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGSDLIM<15:0>:** PTG Step Delay Limit Register bits
Holds a PTG Step delay value representing the number of additional PTG clocks between the start of a Step command and the completion of a Step command.

Note 1: A base Step delay of one PTG clock is added to any value written to the PTGSDLIM register (Step Delay = (PTGSDLIM) + 1).

2: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

REGISTER 24-7: PTGC0LIM: PTG COUNTER 0 LIMIT REGISTER(1)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC0LIM<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTGC0LIM<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-0 **PTGC0LIM<15:0>:** PTG Counter 0 Limit Register bits
May be used to specify the loop count for the PTGJMPC0 Step command or as a limit register for the General Purpose Counter 0.

Note 1: This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).

TABLE 30-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended		
Parameter No.	**Typ.**	**Max.**	**Units**	**Conditions**	
Power-Down Current (I_{PD})(1) – dsPIC33EP32GP50X, dsPIC33EP32MC20X/50X and PIC24EP32GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	200	μA	+85°C	
DC60c	250	500	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP64GP50X, dsPIC33EP64MC20X/50X and PIC24EP64GP/MC20X					
DC60d	25	100	μA	-40°C	3.3V
DC60a	30	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	350	800	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP128GP50X, dsPIC33EP128MC20X/50X and PIC24EP128GP/MC20X					
DC60d	30	100	μA	-40°C	3.3V
DC60a	35	100	μA	+25°C	
DC60b	150	350	μA	+85°C	
DC60c	550	1000	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X and PIC24EP256GP/MC20X					
DC60d	35	100	μA	-40°C	3.3V
DC60a	40	100	μA	+25°C	
DC60b	250	450	μA	+85°C	
DC60c	1000	1200	μA	+125°C	
Power-Down Current (I_{PD})(1) – dsPIC33EP512GP50X, dsPIC33EP512MC20X/50X and PIC24EP512GP/MC20X					
DC60d	40	100	μA	-40°C	3.3V
DC60a	45	100	μA	+25°C	
DC60b	350	800	μA	+85°C	
DC60c	1100	1500	μA	+125°C	

Note 1: I_{PD} (Sleep) current is measured as follows:

- CPU core is off, oscillator is configured in EC mode and external clock is active; OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}, WDT and FSCM are disabled
- All peripheral modules are disabled (PMDx bits are all set)
- The VREGS bit (RCON<8>) = 0 (i.e., core regulator is set to standby while the device is in Sleep mode)
- The VREGSF bit (RCON<11>) = 0 (i.e., Flash regulator is set to standby while the device is in Sleep mode)
- JTAG is disabled

TABLE 30-14: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	3.0	—	3.6	V	
D132b	VPEW	VDD for Self-Timed Write	3.0	—	3.6	V	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current during Programming(2)	—	10	—	mA	
D136	IPEAK	Instantaneous Peak Current During Start-up	—	—	150	mA	
D137a	TPE	Page Erase Time	17.7	—	22.9	ms	TPE = 146893 FRC cycles, TA = +85°C (See **Note 3)**
D137b	TPE	Page Erase Time	17.5	—	23.1	ms	TPE = 146893 FRC cycles, TA = +125°C (See **Note 3)**
D138a	TWW	Word Write Cycle Time	41.7	—	53.8	µs	TWW = 346 FRC cycles, TA = +85°C (See **Note 3)**
D138b	TWW	Word Write Cycle Time	41.2	—	54.4	µs	TWW = 346 FRC cycles, TA = +125°C (See **Note 3)**

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

2: Parameter characterized but not tested in manufacturing.

3: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `011111` (for Minimum), TUN<5:0> = `100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 30-19) and the value of the FRC Oscillator Tuning register (see Register 9-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 "Programming Operations"**.

FIGURE 32-9: TYPICAL FRC FREQUENCY @ V_{DD} = 3.3V

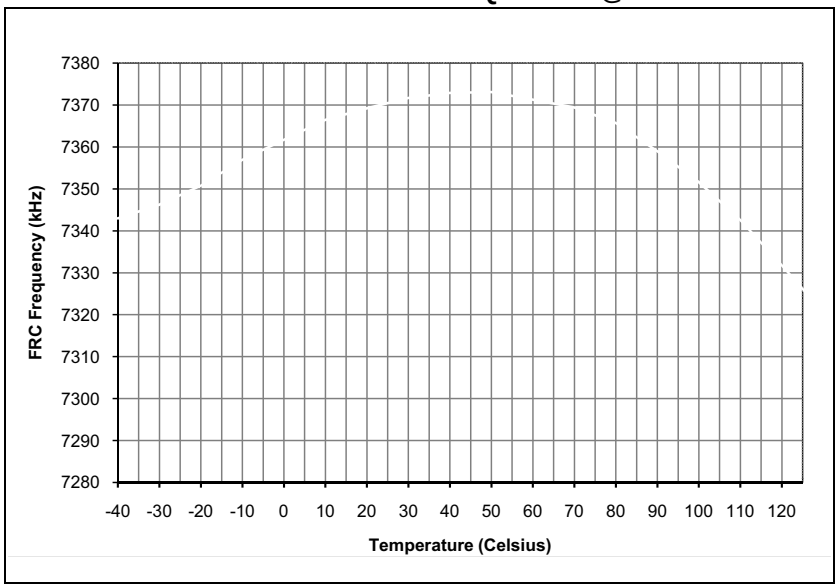


FIGURE 32-10: TYPICAL LPRC FREQUENCY @ V_{DD} = 3.3V

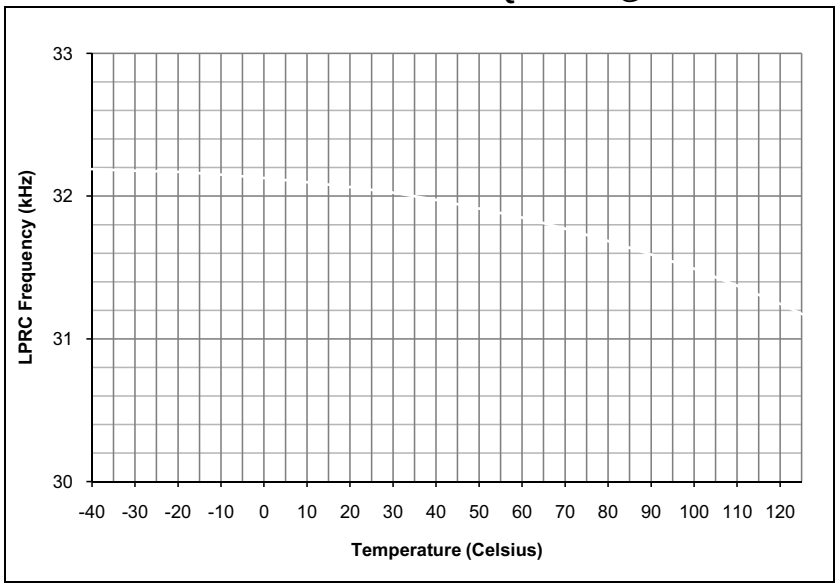
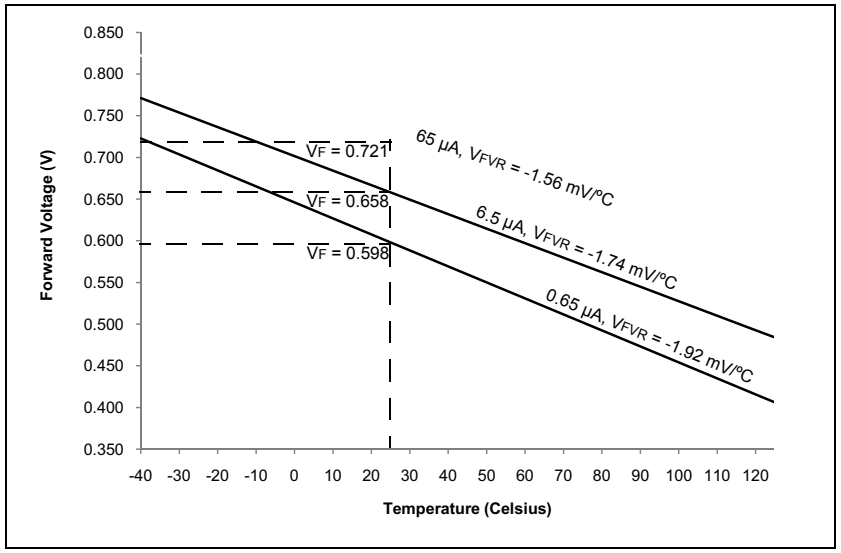
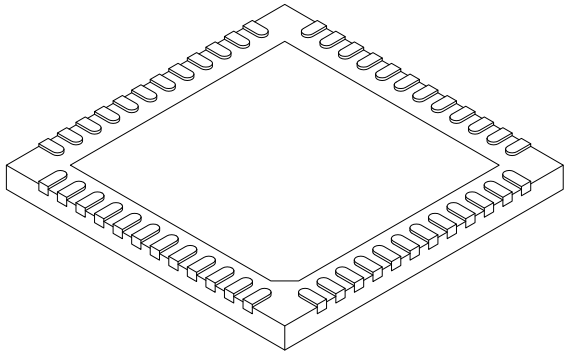


FIGURE 32-11: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		48	
Pitch	e		0.40 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.127 REF	
Overall Width	E		6.00 BSC	
Exposed Pad Width	E2	4.45	4.60	4.75
Overall Length	D		6.00 BSC	
Exposed Pad Length	D2	4.45	4.60	4.75
Contact Width	b	0.15	0.20	0.25
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

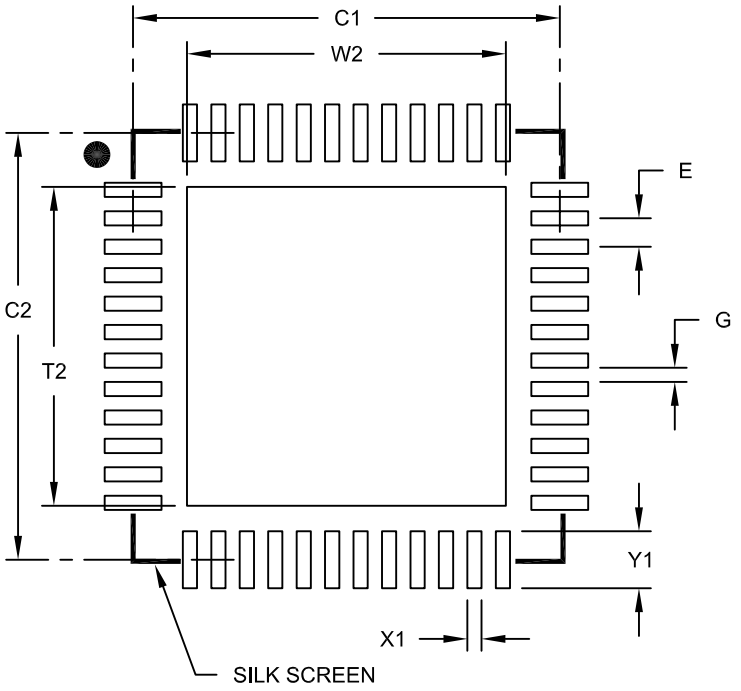
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN]
With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A